OK to enker

Appl. No. 10/008,337 Amendment and/or Response Reply to final Office action of 16 December 2003

From-PHILIPS ELECTRONICS ICS

Page 2 of 5

Amendments to the Claims:

A listing of the entire set of pending claims (including amendments to the claims, if any) is submitted herewith per 37 CFR 1.121. This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

- 1-12 (Canceled)
- 13. (Currently amended) The device of claim-12_14 wherein the weakened regions comprise grooves in one or both faces of the rigid layer.
- 14. (Currently amended) The device of claim 12 An electronic device comprising a layer of rigid material having electronic components mounted directly thereon, contiguous portions of the rigid layer being defined by weakened regions of the rigid layer, and flexible connectors extending between components on different portions, wherein the rigid layer is mounted over a flexible substrate.
- 15. (Currently amended) The device of claim-12 14 wherein the connectors comprise electroplated metal.
- 16. (Currently amended) The device of claim-12_14 wherein the connectors comprise a bridge-like portion.
- 17 (Canceled)
- 18. (Currently amended) The device of claim-17-20 wherein the rigid layer has been divided into the contiguous portions along weakened regions of the rigid layer.

Atty. Docket No. GB-000164